

The documentation and process conversion measures necessary to comply with this revision shall be completed by 25 June 2015.

INCH-POUND

MIL-PRF-19500/758A
 25 March 2015
 SUPERSEDING
 MIL-PRF-19500/758
 28 June 2010

PERFORMANCE SPECIFICATION SHEET

TRANSISTOR, FIELD EFFECT, RADIATION HARDENED
 N-CHANNEL, SILICON, DEVICE TYPES 2N7609U8 AND 2N7609U8C,
 JANTXV AND JANS

This specification is approved for use by all Departments and Agencies of the Department of Defense.

The requirements for acquiring the product described herein shall consist of this specification sheet and [MIL-PRF-19500](#).

1. SCOPE

1.1 Scope. This specification covers the performance requirements for N-channel, enhancement-mode, MOSFET, radiation hardened (total dose and single event effects (SEE)), power transistor. Two levels of product assurance (JANTXV and JANS) are provided for each device type as specified in [MIL-PRF-19500](#), with avalanche energy maximum rating (E_{AS}) and maximum avalanche current (I_{AS}) for use in particular power-switching applications. See 6.7 for JANHC and JANKC die versions.

1.2 Package outlines. The device package outlines are as follows: SMD-0.2, U8 (metal lid) and U8C (ceramic lid) in accordance with [figure 1](#). The dimensions and topography for JANHC and JANKC unencapsulated die are as listed in slash sheet [MIL-PRF-19500/741](#).

1.3 Maximum ratings. $T_A = +25^\circ\text{C}$, unless otherwise specified.

Type	P_T (1) $T_C = +25^\circ\text{C}$	P_T $T_A = +25^\circ\text{C}$	$R_{\theta JC}$ (2)	V_{DS}	V_{DG}	V_{GS}	I_{D1} (3) (4) $T_C = +25^\circ\text{C}$	I_{D2} (3) (4) $T_C = +100^\circ\text{C}$	I_S	I_{DM} (5)	T_J and T_{STG}
	<u>W</u>	<u>W</u>	<u>°C/W</u>	<u>V dc</u>	<u>V dc</u>	<u>V dc</u>	<u>A dc</u>	<u>A dc</u>	<u>A dc</u>	<u>A (pk)</u>	<u>°C</u>
2N7609U8, 2N7609U8C	23	0.8	5.4	100	100	±10	6.5	4.1	6.5	26	-55 to +150

- (1) Derate linearly by 0.185 W/°C for $T_C > +25^\circ\text{C}$.
- (2) See [figure 2](#), thermal impedance curves.
- (3) The following formula derives the maximum theoretical I_D limit. I_D is limited by package and internal construction.

$$I_D = \sqrt{\frac{T_{JM} - T_C}{(R_{\theta JC}) \times (R_{DS(on)} \text{ at } T_{JM})}}$$

- (4) See [figure 3](#), maximum drain current graph.
- (5) $I_{DM} = 4 \times I_{D1}$ as calculated in note (3).

* Comments, suggestions, or questions on this document should be addressed to DLA Land and Maritime, ATTN: VAC, P.O. Box 3990, Columbus, OH 43218-3990, or emailed to Semiconductor@dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at <https://assist.dla.mil/>.



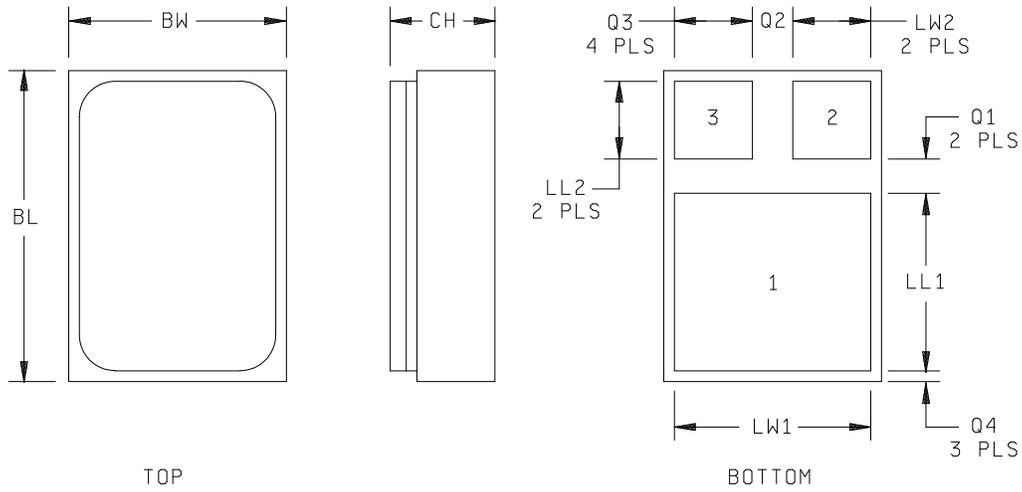
1.4 Primary electrical characteristics at $T_C = +25^\circ\text{C}$.

Type	Min $V_{(BR)DSS}$ $V_{GS} = 0$ $I_D = 0.25\text{mA}$ dc	$V_{GS(TH)1}$ $V_{DS} \geq V_{GS}$ $I_D = 0.25\text{ mA dc}$	Max I_{DSS1} $V_{GS} = 0$ $V_{DS} = 80\%$ of rated V_{DS}	Max $r_{DS(on)}$ (1) $V_{GS} = 4.5\text{V}$, $I_D = I_{D2}$		E_{AS}	I_{AS}
				$T_J = +25^\circ\text{C}$	$T_J = +150^\circ\text{C}$		
	<u>V dc</u>	<u>V dc</u> Min Max	<u>$\mu\text{A dc}$</u>	<u>Ω</u>	<u>Ω</u>	<u>mJ</u>	<u>A</u>
2N7609U8, 2N7609U8C	100	1.0 2.0	1.0	0.29	0.55	21	6.5

(1) Pulsed (see 4.5.1).

- * 1.5 Part or Identifying Number (PIN). The PIN is in accordance with MIL-PRF-19500, and as specified herein. See 6.4 for PIN construction example and 6.5 for a list of available PINs.
- * 1.5.1 JAN certification mark and quality level for encapsulated devices. The quality level designators for encapsulated devices that are applicable for this specification sheet from the lowest to the highest level are as follows: "JANTXV" and "JANS".
- * 1.5.2 JAN brand and quality level designators for unencapsulated devices (die). See 6.7 for unencapsulated devices.
- * 1.5.3 Radiation hardness assurance (RHA) designator. The RHA levels that are applicable for this specification sheet from lowest to highest are as follows: "M", "D", "P", "L", "R", "F", and "G".
- * 1.5.4 Device type. The designation system for the device types of transistors covered by this specification sheet are as follows.
 - * 1.5.4.1 First number and first letter symbols. The transistors of this specification sheet are identified by the first number and letter symbols "2N".
 - * 1.5.4.2 Second number symbols. The second number symbols for the transistor covered by this specification sheet are as follows: "7609".
 - * 1.5.4.3 Suffix letters. The suffix letters "U8" and "U8C" are used on devices that are packaged in the SMD-0.2 package of figure 1.
- * 1.5.5 Lead finish. The lead finishes applicable to this specification sheet are listed on QML-19500.

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Symbol	Dimensions				Note
	Inches		Millimeters		
	Min	Max	Min	Max	
BL	.305	.321	7.75	8.15	
BW	.200	.226	5.08	5.74	
CH (for U8)		.097		2.46	U8 Only
CH (for U8C)		.106		2.69	U8C Only
LH	.010	.020	0.25	0.51	U8 Only
LW1	.193	.203	4.90	5.16	
LW2	.076	.086	1.93	2.19	
LL1	.174	.184	4.42	4.67	
LL2	.074	.084	1.88	2.13	
LS1	0.150 BSC		3.81 BSC		U8 Only
LS2	0.075 BSC		1.91 BSC		U8 Only
Q1	.030	.040	0.76	1.02	
Q2	.030	.040	0.76	1.02	
Q3	.01 REF		0.25 REF		
Q4	.01 REF		0.25 REF		
TERM 1	Drain				
TERM 2	Gate				
TERM 3	Source				

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. The lid shall be electrically isolated from the drain, gate and source.
4. In accordance with ASME Y14.5M, diameters are equivalent to ϕx symbology.

FIGURE 1. Physical dimensions for SMD-0.2, 2N7609U8 and 2N7609U8C.

2. APPLICABLE DOCUMENTS

- * 2.1 General. The documents listed in this section are specified in sections 3 and 4 **Error! Reference source not found.** of this specification. This section does not include documents cited in other sections of this specification or recommended for additional information or as examples. While every effort has been made to ensure the completeness of this list, document users are cautioned that they must meet all specified requirements of documents cited in sections 3 and 4 **Error! Reference source not found.** of this specification, whether or not they are listed.

2.2 Government documents.

2.2.1 Specifications, standards, and handbooks. The following specifications, standards, and handbooks form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATIONS

MIL-PRF-19500 - Semiconductor Devices, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-750 - Test Methods for Semiconductor Devices.

- * (Copies of these documents are available online at <http://quicksearch.dla.mil/>).

2.3 Order of precedence. Unless otherwise noted herein or in the contract, in the event of a conflict between the text of this document and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 General. The individual item requirements shall be as specified in **MIL-PRF-19500** and as modified herein.

3.2 Qualification. Devices furnished under this specification shall be products that are manufactured by a manufacturer authorized by the qualifying activity for listing on the applicable qualified manufacturer's list (QML) before contract award (see 4.2 and 6.3).

3.3 Abbreviations, symbols, and definitions. Abbreviations, symbols, and definitions used herein shall be as specified in **MIL-PRF-19500** and as follows.

I_{AS} Rated avalanche current, non-repetitive
nC nano Coulomb.

3.4 Interface and physical dimensions. Interface and physical dimensions shall be as specified in **MIL-PRF-19500**, and on **figure 1** (SMD-0.2, U8 and U8C) herein.

- * 3.4.1 Lead finish. Lead finish shall be solderable in accordance with **MIL-PRF-19500**, **MIL-STD-750**, and herein. Where a choice of lead finish is desired, it shall be specified in the acquisition document (see 6.2) and should be specified by the PIN (see 1.5).

3.4.2 Internal construction. Multiple chip construction is not permitted to meet the requirements of this specification.

3.5 Electrostatic discharge protection. The devices covered by this specification require electrostatic discharge protection.

3.5.1 Handling. Metal oxide semiconductor (MOS) devices must be handled with certain precautions to avoid damage due to the accumulation of static charge. However, the following handling practices are recommended (see 3.5).

- a. Devices should be handled on benches with conductive handling devices.
- b. Ground test equipment, tools, and personnel handling devices.
- c. Do not handle devices by the leads.
- d. Store devices in conductive foam or carriers.
- e. Avoid use of plastic, rubber, or silk in MOS areas.
- f. Maintain relative humidity above 50 percent if practical.
- g. Care should be exercised during test and troubleshooting to apply not more than maximum rated voltage to any lead.
- h. Gate must be terminated to source, $R \leq$ or 100 k Ω , whenever bias voltage is applied drain to source.

3.6 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in 1.3, 1.4, and table I.

3.7 Electrical test requirements. The electrical test requirements shall be as specified in table I.

3.8 Marking. Marking shall be in accordance with MIL-PRF-19500. At the option of the manufacturer, marking of the country of origin may be omitted from the body of the transistor but shall be retained on the initial container.

3.9 Workmanship. Semiconductor devices shall be processed in such a manner as to be uniform in quality and shall be free from other defects that will affect life, serviceability, or appearance.

4. VERIFICATION

4.1 Classification of inspections. The inspection requirements specified herein are classified as follows:

- a. Qualification inspection (see 4.2).
- b. Screening (see 4.3).
- c. Conformance inspection (see 4.4 and tables I and II).

4.2 Qualification inspection. Qualification inspection shall be in accordance with MIL-PRF-19500 and as specified herein.

4.2.1 Group E qualification. Group E inspection shall be performed for qualification or re-qualification only. In case qualification was awarded to a prior revision of the specification sheet that did not request the performance of table III tests, the tests specified in table III herein that were not performed in the prior revision shall be performed on the first inspection lot of this revision to maintain qualification.

- * 4.2.1.1 Single event effects (SEE). SEE shall be performed at initial qualification and after process or design changes which may affect radiation hardness (see table III and table IV). Upon qualification, manufacturers shall provide the verification test conditions from section 5 of method 1080 of MIL-STD-750 that were used to qualify the device for inclusion into section 6 of the slash sheet. End-point measurements shall be in accordance with table II. SEE characterization data shall be made available upon request of the qualifying or acquiring activity.

4.3 Screening (JANS and JANTXV). Screening shall be in accordance with table E-IV of MIL-PRF-19500, and as specified herein. The following measurements shall be made in accordance with table I herein. Devices that exceed the limits of table I herein shall not be acceptable.

Screen (see table E-IV of MIL-PRF-19500) (1) (2)	Measurement	
	JANS level	JANTXV levels
(3)	Gate stress test (see 4.3.1)	Gate stress test (see 4.3.1)
(3)	Method 3470 of MIL-STD-750, E _{AS} (see 4.3.2)	Method 3470 of MIL-STD-750, E _{AS} (see 4.3.2)
(3) 3c	Method 3161 of MIL-STD-750, thermal impedance, (see 4.3.3)	Method 3161 of MIL-STD-750, thermal impedance, (see 4.3.3)
9	Subgroup 2 of table I herein, I _{GSSF1} , I _{GSSR1} , I _{DSS1} as a minimum	Not applicable
10	Method 1042 of MIL-STD-750, test condition B	Method 1042 of MIL-STD-750, test condition B
11	I _{GSSF1} , I _{GSSR1} , I _{DSS1} , r _{DS(on)1} , V _{GS(TH)1} Subgroup 2 of table I herein $\Delta I_{GSSF1} = \pm 20 \text{ nA dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta I_{GSSR1} = \pm 20 \text{ nA dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta I_{DSS1} = \pm 1.0 \text{ } \mu\text{A dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$	I _{GSSF1} , I _{GSSR1} , I _{DSS1} , r _{DS(on)1} , V _{GS(TH)1} Subgroup 2 of table I herein
12	Method 1042 of MIL-STD-750, test condition A	Method 1042 of MIL-STD-750, test condition A
13	Subgroups 2 and 3 of table I herein $\Delta I_{GSSF1} = \pm 20 \text{ nA dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta I_{GSSR1} = \pm 20 \text{ nA dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta I_{DSS1} = \pm 1.0 \text{ } \mu\text{A dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta r_{DS(on)1} = \pm 20 \text{ percent of initial value}$ $\Delta V_{GS(th)1} = \pm 20 \text{ percent of initial value}$	Subgroup 2 of table I herein $\Delta I_{GSSF1} = \pm 20 \text{ nA dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta I_{GSSR1} = \pm 20 \text{ nA dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta I_{DSS1} = \pm 1.0 \text{ } \mu\text{A dc or } \pm 100 \text{ percent of initial value, whichever is greater.}$ $\Delta r_{DS(on)1} = \pm 20 \text{ percent of initial value}$ $\Delta V_{GS(th)1} = \pm 20 \text{ percent of initial value}$

(1) At the end of the test program, I_{GSSF1}, I_{GSSR1}, and I_{DSS1} are measured.

(2) An out-of-family program to characterize I_{GSSF1}, I_{GSSR1}, I_{DSS1}, and V_{GS(th)1} shall be invoked.

(3) Shall be performed anytime after temperature cycling, screen 3a; JANTXV level does not need to be repeated in screening requirements.

4.3.1 Gate stress test. Apply $V_{GS} = 15\text{ V}$, minimum for $t = 250\ \mu\text{sec.}$, minimum.

4.3.2 Single pulse avalanche energy (E_{AS}).

- a. Peak current $I_{AS} = I_{D1}$.
- b. Inductance $L = \left[\frac{2E_{AS}}{(I_{D1})^2} \right] \left[\frac{V_{BR} - V_{DD}}{V_{BR}} \right]$ mH minimum.
- c. Gate to source resistor R_{GS} : $25\ \Omega \leq R_{GS} \leq 200\ \Omega$.
- d. Supply voltage $V_{DD} = 50\text{ V dc}$ maximum.
- e. Initial case temperature $T_C = +25^\circ\text{ C}, -5^\circ\text{ C}, +10^\circ\text{ C}$.
- f. Gate voltage, $V_{GS} = 5\text{ V dc}$ (up to rated V_{GS})
- g. Number of pulses to be applied: 1 pulse minimum.

4.3.3 Thermal impedance. The thermal impedance measurements shall be performed in accordance with method 3161 of [MIL-STD-750](#) using the guidelines in that method for determining I_M, I_H, t_H, t_{SW} , (and V_H where appropriate). Measurement delay time (t_{MD}) = 70 μs max. See [table III](#), group E, subgroup 4 herein.

4.4 Conformance inspection. Conformance inspection shall be in accordance with [MIL-PRF-19500](#).

4.4.1 Group A inspection. Group A inspection shall be conducted in accordance with table E-V of [MIL-PRF-19500](#) and [table I](#) herein.

* 4.4.2 Group B inspection. Group B inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-VIA (JANS) and table E-VIB (JANTXV) of [MIL-PRF-19500](#), and as follows.

4.4.2.1 Group B inspection, table E-VIA (JANS) of [MIL-PRF-19500](#).

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
B3	1051	Test condition G, 100 cycles.
B3	2077	Scanning electron microscope (SEM) qualification may be performed anytime prior to lot formation.
* B4	1042	Intermittent operation life, condition D. No heat sink or forced-air cooling on the device shall be permitted during the on cycle. $t_{on} = 30$ seconds minimum.
B5	1042	Accelerated steady-state gate bias, condition B, $V_{GS} = \text{rated}$; $T_A = +175^\circ\text{C}$, $t = 24$ hours minimum; or $T_A = +150^\circ\text{C}$, $t = 48$ hours minimum.
B5	1042	Accelerated steady-state reverse bias, condition A, $V_{DS} = \text{rated}$; $T_A = +175^\circ\text{C}$, $t = 120$ hours minimum; or $T_A = +150^\circ\text{C}$, $t = 240$ hours minimum.
B5	2037	Test condition D.

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- * 4.4.2.2 Group B inspection, table E-VIB (JANTXV) of MIL-PRF-19500.

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
B2	1051	Test condition G, 25 cycles.

- * B3 1042 Intermittent operation life, condition D. No heat sink or forced-air cooling on the device shall be permitted during the on cycle. $t_{on} = 30$ seconds minimum.

- * 4.4.3 Group C inspection. Group C inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-VII of MIL-PRF-19500 and as follows.

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
C2	2036	Terminal strength is not applicable.
C5	3161	Thermal resistance, see 4.5.2, $R_{\theta JC(max)} = 5.4$ °C/W.

- * C6 1042 Intermittent operation life, condition D. No heat sink or forced-air cooling on the device shall be permitted during the on cycle. $t_{on} = 30$ seconds minimum.

4.4.4 Group D inspection. Group D inspection shall be conducted in accordance with table E-VIII of MIL-PRF-19500 and table II herein.

- * 4.4.5 Group E inspection. Group E inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-IX of MIL-PRF-19500 and as specified in table III herein.

4.4.5.1 SEE. Design capability shall be tested on the initial qualification and thereafter whenever a major die design or process change is introduced. See the design safe operation area figures. End-point measurements shall be in accordance with table III.

4.5 Methods of inspection. Methods of inspection shall be as specified in the appropriate tables and as follows.

4.5.1 Pulse measurements. Conditions for pulse measurement shall be as specified in section 4 of MIL-STD-750.

4.5.2 Thermal resistance. The thermal resistance measurements shall be performed in accordance with method 3161 of MIL-STD-750 using the guidelines in that method for determining I_M , I_H , t_H , t_{SW} (and V_H where appropriate). Measurement delay time (t_{MD}) = 70 μ s max. See table E-IX of MIL-PRF-19500, group E, subgroup 4.

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TABLE I. Group A inspection.

Inspection 1/	MIL-STD-750		Symbol	Limits		Unit
	Method	Condition		Min	Max	
<u>Subgroup 1</u>						
Visual and mechanical inspection	2071					
<u>Subgroup 2</u>						
Thermal impedance 2/	3161	See 4.3.3	$Z_{\theta JC}$			°C/W
Breakdown voltage drain to source	3407	Bias condition C, $V_{GS} = 0$, $I_D = 0.25$ mA dc	$V_{(BR)DSS}$	100		V dc
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS}$, $I_D = 0.25$ mA dc	$V_{GS(TH)1}$	1.0	2.0	V dc
Gate current	3411	$V_{GS} = +10$ V dc, bias condition C, $V_{DS} = 0$	I_{GSSF1}		+100	nA dc
Gate current	3411	$V_{GS} = -10$ V dc, bias condition C, $V_{DS} = 0$	I_{GSSR1}		-100	nA dc
Drain current	3413	$V_{GS} = 0$, bias condition C, $V_{DS} = 80$ percent of rated V_{DS} ,	I_{DSS1}		1.0	μA dc
Static drain to source on-state resistance	3421	$V_{GS} = 4.5$ V dc, condition A, pulsed (see 4.5.1), $I_D = I_{D2}$	$r_{DS(ON)1}$		0.29	Ω
* Forward voltage	4011	$V_{GS} = 0$, condition A, $I_D = I_{D1}$	V_{SD}		1.2	V dc
<u>Subgroup 3</u>						
High temperature operation		$T_C = T_J = +125^\circ\text{C}$				
Gate current	3411	$V_{GS} = \pm 10$ V dc, bias condition C, $V_{DS} = 0$	I_{GSS2}		±200	nA dc
Drain current	3413	$V_{GS} = 0$, bias condition C, $V_{DS} = 80$ percent of rated V_{DS}	I_{DSS2}		10	μA dc

See footnotes at end of table.

* TABLE I. Group A inspection - Continued.

Inspection 1/	MIL-STD-750		Symbol	Limits		Unit
	Method	Condition		Min	Max	
<u>Subgroup 3</u> - continued						
Static drain to source on-state resistance	3421	$V_{GS} = 4.5V$ dc, condition A, pulsed (see 4.5.1), $I_D = I_{D2}$	$r_{DS(ON)2}$		0.46	Ω
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS}$, $I_D = 0.25$ mA dc	$V_{GS(TH)2}$	0.5		V dc
Low temperature operation		$T_C = T_J = -55^\circ C$				
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS(TH)3}$, $I_D = 0.25$ mA dc	$V_{GS(TH)3}$		3.0	V dc
<u>Subgroup 4</u>						
Forward transconductance	3475	$I_D = I_{D2}$, $V_{DD} = 10$ V dc (see 4.5.1)	g_{FS}	3.5		S
Gate series resistance	3402	Condition A.	R_G		15	Ω
<u>Subgroup 5</u>						
Safe operating area test (high voltage)	3474	See figure 4, $t_p = 10$ ms min. $V_{DS} = 80$ percent of max. rated V_{DS}				
Electrical measurements		See table I, subgroup 2				
<u>Subgroup 6</u>						
Not applicable						

See footnotes at end of table.

*

TABLE I. Group A inspection - Continued.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Condition		Min	Max	
<u>Subgroup 7</u>						
Gate charge	3471	Condition B. $I_D = I_{D1}$, $V_{GS} = 4.5 \text{ V dc}$ $V_{DD} = 50 \text{ percent of rated } V_{DS}$				
On-state gate charge			$Q_{G(\text{on})}$	13.5	nC	
On gate to source charge			Q_{GS}	4.0	nC	
On gate to drain charge			Q_{GD}	8.0	nC	
Turn-off gate charge			$Q_{G(\text{off})}$	13.5	nC	
Off gate to source charge			Q_{GS}	4.0	nC	
Off gate to drain charge			Q_{GD}	8.0	nC	
Reverse recovery time	3473	$di/dt = -100 \text{ A}/\mu\text{s}$, $V_{DD} \leq 25 \text{ V}$ $I_D = I_{D1}$	t_{rr}	215	ns	

1/ For sampling plan, see [MIL-PRF-19500](#).

2/ This test required for the following end-point measurements only:
 Group B, subgroups 2 and 3 (JANTXV).
 Group B, subgroups 3 and 4 (JANS).
 Group C, subgroup 2 and 6.
 Group E, subgroup 1.

* TABLE II. Group D inspection.

Inspection 1/ 2/ 3/	MIL-STD-750		Symbol	Pre-irradiation limits		Post-irradiation limits				Unit
	Method	Conditions		R, F and G		R		F and G 4/		
				Min	Max	Min	Max	Min	Max	
<u>Subgroup 1</u>										
Not applicable										
<u>Subgroup 2</u>		$T_C = + 25^\circ\text{C}$								
Steady-state total dose irradiation (V_{GS} bias) 5/	1019	$V_{GS} = 10 \text{ V};$ $V_{DS} = 0$								
Steady-state total dose irradiation (V_{DS} bias) 5/	1019	$V_{GS} = 0;$ $V_{DS} = 80$ percent of rated V_{DS} (pre-irradiation)								
End-point electricals:										
Breakdown voltage, drain to source	3407	$V_{GS} = 0 \text{ V}; I_D = 0.25\text{mA};$ bias condition C	$V_{(BR)DSS}$	100		100		100		V dc
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS}$ $I_D = 0.25 \text{ mA}$	$V_{GS(th)1}$	1.0	2.0	1.0	2.0	1.0	2.0	V dc
Gate current	3411	$V_{GS} = +10 \text{ V}; V_{DS} = 0$ bias condition C	I_{GSSF1}		100		100		100	nA dc
Gate current	3411	$V_{GS} = -10 \text{ V}; V_{DS} = 0$ bias condition C	I_{GSSR1}		-100		-100		-100	nA dc
Drain current	3413	$V_{GS} = 0, V_{DS} = 80$ percent of rated V_{DS} (pre-irradiation) bias condition C,	I_{DSS}		1.0		1.0		1.0	μA dc
Static drain to source on-state voltage	3405	$V_{GS} = 4.5 \text{ V}; I_D = I_{D2}$ condition A pulsed (see 4.5.1)	$V_{DS(on)}$		1.066		1.066		1.066	V dc
* Forward voltage source drain diode	4011	$V_{GS} = 0; I_D = I_{D1}$ bias condition A	V_{SD}		1.2		1.2		1.2	V dc

1/ For sampling plan see MIL-PRF-19500.

2/ Group D qualification may be performed prior to lot formation. Wafers qualified to these group D QCI requirements may be used for any other specification sheet utilizing the same die design.

3/ At the manufacturer's option, group D samples need not be subjected to the screening tests, and may be assembled in its qualified package or in any qualified package that the manufacturer has data to correlate the performance to the designated package.

4/ The higher level designation G represents devices which pass end-points at all lower level designation.

5/ Separate samples shall be pulled for each bias.

*

TABLE III. Group E inspection (all quality levels) for qualification or re-qualification only.

Inspection	MIL-STD-750		Sample plan
	Method	Conditions	
<u>Subgroup 1</u>			
Temperature cycling	1051	Test condition G, 500 cycles	45 devices c = 0
Hermetic seal Fine leak Gross leak	1071	As applicable	
Electrical measurements		Table I, subgroup 2 herein.	
<u>Subgroup 2 1/</u>			
Steady-state gate bias	1042	Condition B, 1,000 hours.	45 devices c = 0
Electrical measurements		Table I, subgroup 2 herein.	
Steady-state reverse bias	1042	Condition A, 1,000 hours.	
Electrical measurements		Table I, subgroup 2 herein.	
<u>Subgroup 3</u>			
Switching time test	3472	$I_D = I_{D1}$, $V_{GS} = 5$ V dc, $R_G = 7.5 \Omega$, $V_{DD} = 50$ percent of rated V_{DS} Maximum limits $t_{D(on)} = 18$ ns; $t_r = 90$ ns $t_{D(off)} = 45$ ns; $t_f = 32$ ns	45 devices c = 0
<u>Subgroup 4</u>			
Thermal impedance curves		See MIL-PRF-19500.	Sample size N/A
<u>Subgroup 10</u>			
Commutating diode for safe operating area test procedure for measuring dv/dt during reverse recovery of power MOSFET transistors or insulated gate bipolar transistors	3476	Test conditions shall be derived by the manufacturer	22 devices c = 0

1/ A separate sample for each test shall be pulled.

2/ Group E qualification of SEE testing may be performed prior to lot formation. Qualification may be extended to other specification sheets utilizing the same structurally identical die design.

3/ Device qualification to a higher level linear energy transfer (LET) is sufficient to qualify all lower level LETs.

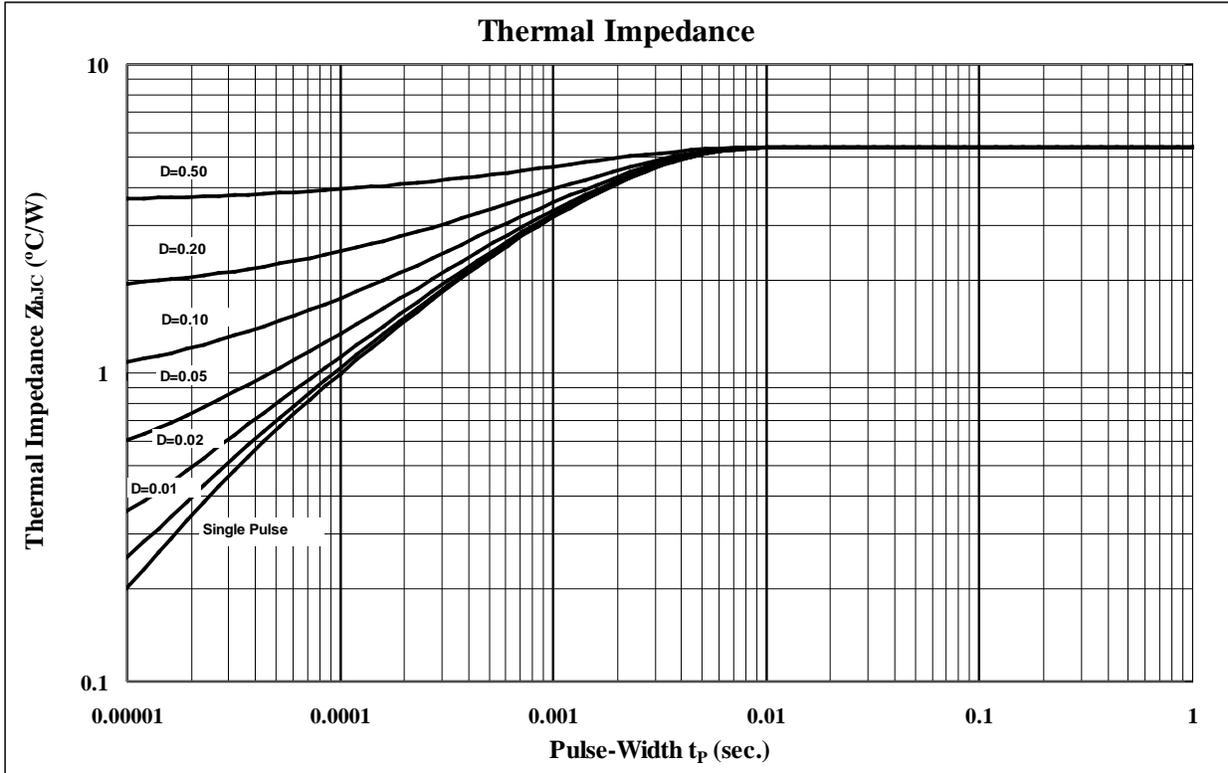


FIGURE 2. Thermal impedance curves.

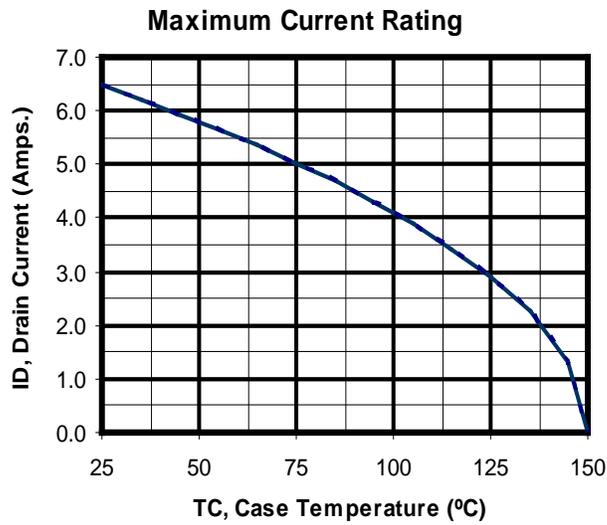


FIGURE 3. Maximum drain current versus case temperature graphs.

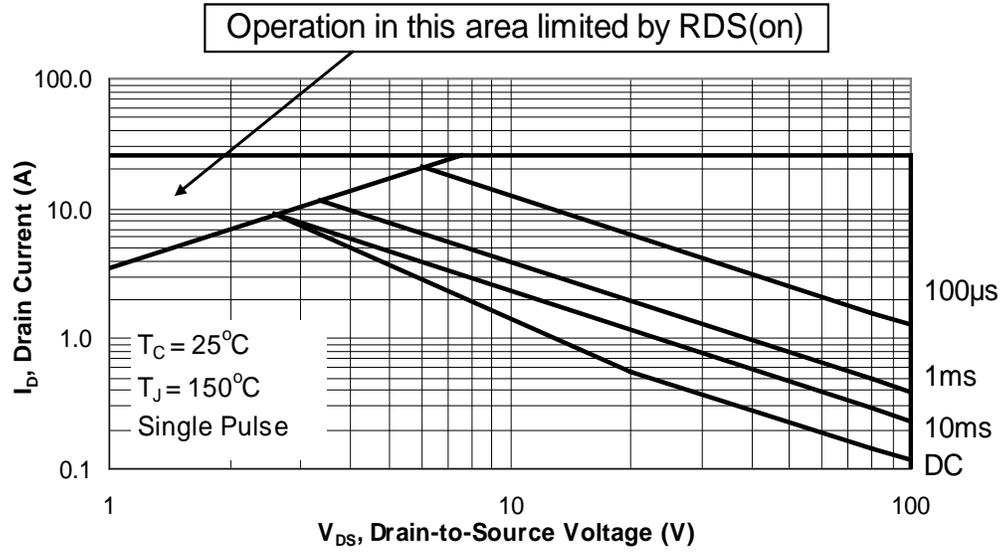


FIGURE 4. Safe operating area graph.

5. PACKAGING

5.1 Packaging. For acquisition purposes, the packaging requirements shall be as specified in the contract or order (see 6.2). When packaging of materiel is to be performed by DoD or in-house contractor personnel, these personnel need to contact the responsible packaging activity to ascertain packaging requirements. Packaging requirements are maintained by the Inventory Control Point's packaging activities within the Military Service or Defense Agency, or within the Military Service's system commands. Packaging data retrieval is available from the managing Military Department's or Defense Agency's automated packaging files, CD-ROM products, or by contacting the responsible packaging activity.

6. NOTES

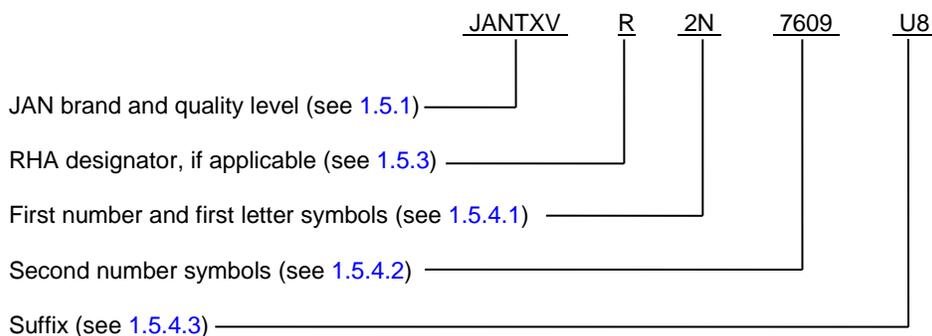
(This section contains information of a general or explanatory nature that may be helpful, but is not mandatory. The notes specified in MIL-PRF-19500 are applicable to this specification.)

6.1 Intended use. Semiconductors conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

6.2 Acquisition requirements. Acquisition documents should specify the following:

- a. Title, number, and date of this specification.
 - b. Packaging requirements (see 5.1).
 - c. Lead finish (see 3.4.1).
 - * d. The complete Part or Identifying Number (PIN), see 1.5 and 6.4.
 - * e. For acquisition of RHA designated devices, table II, subgroup 1 testing of group D herein is optional. If subgroup 1 is desired, it should be specified in the contract or order.
 - * f. If SEE testing data is desired, it should be specified in the contract or order.
 - * g. If specific SEE characterization conditions are desired (see section 6.6 and table IV), manufacturer's cage code should be specified in the contract or order.
- * 6.3 Qualification. With respect to products requiring qualification, awards will be made only for products which are, at the time of award of contract, qualified for inclusion in Qualified Manufacturers List (QML 19500) whether or not such products have actually been so listed by that date. The attention of the contractors is called to these requirements, and manufacturers are urged to arrange to have the products that they propose to offer to the Federal Government tested for qualification in order that they may be eligible to be awarded contracts or orders for the products covered by this specification. Information pertaining to qualification of products may be obtained from DLA Land and Maritime, ATTN: VQE, P.O. Box 3990, Columbus, OH 43218-3990 or e-mail vqe.chief@dla.mil. An online listing of products qualified to this specification may be found in the Qualified Products Database (QPD) at <https://assist.dla.mil>.

- * 6.4 PIN construction example. The PINs for encapsulated devices are construction using the following form.



- * 6.5 List of PINs. The following is a list of possible PINs available on this specification sheet.

PINs for devices of the "TXV" quality level	PINs for devices of the "TXV" quality level with RHA (1)	PINs for devices of the "S" quality level	PINs for devices of the "S" quality level with RHA (1)
JANTXV2N77609U8	JANTXV#2N7609U8	JANS2N7609U8	JANS#2N7609U8
JANTXV2N7609U8C	JANTXV#2N7609U8C	JANS2N7609U8C	JANS#2N7609U8C

(1) The number sign (#) represent one of six RHA designators available (M, D, P, L, R, F, or G).

- * 6.6 Cross-reference list. The following table shows the generic P/N and its associated military P/N (without JAN and RHA prefix). Devices covered by this specification are substitutable for the manufacturer's and user's Part or Identifying Number (PIN). This information in no way implies that manufacturer's PIN's are suitable for the military PIN.

Generic P/N	Military P/N	Note
IRHLNM77110	2N7609U8	Metal lid
IRHLNMC77110	2N7609U8C	Ceramic lid

6.7 JANC die versions. The JANHC and JANKC die versions of these devices are covered under specification sheet [MIL-PRF-19500/741](#).

* 6.8 Application data.

* 6.8.1 Manufacturer specific irradiation data. Each manufacturer qualified to this slash sheet has characterized its devices to the requirements of [MIL-STD-750](#) method 1080 and as specified herein. Since each manufacturer's characterization conditions can be different and can vary by the version of method 1080 qualified to, the [MIL-STD-750](#) method 1080 revision version date and conditions used by each manufacturer for characterization have been listed here (see [table IV](#)) for information only. SEE conditions and figures listed in section 6 are current as of the date of this specification sheet, please contact the manufacturer for the most recent conditions.

TABLE IV. Manufacturers characterization conditions.

Manufacturers CAGE	Inspection	MIL-STD-750		Sample plan
		Method	Conditions	
No manufacturers are currently qualified to the SEE requirements	SEE <u>1/</u>	1080	See MIL-STD-750 method 1080	3 devices
	Electrical Measurements		I _{GSSF1} , I _{GSSR1} , and I _{DSS1} in accordance with table I , subgroup 2	
	Electrical Measurement		I _{GSSF1} , I _{GSSR1} , and I _{DSS1} in accordance with table I , subgroup 2	
<div style="border: 1px solid black; padding: 5px; width: fit-content; margin: 0 auto;"> Upon qualification, all manufacturers will provide the verification test conditions to be added to this table. </div>				

1/ I_{GSSF1}, I_{GSSR1}, I_{DSS1} are examined before and following SEE irradiation to determine acceptability for each bias condition. Other test conditions in accordance with [table I](#), subgroup 2, may be performed at the manufacturer's option.

6.9 Changes from previous issue. The margins of this specification are marked with asterisks to indicate where changes from the previous issue were made. This was done as a convenience only and the Government assumes no liability whatsoever for any inaccuracies in these notations. Bidders and contractors are cautioned to evaluate the requirements of this document based on the entire content irrespective of the marginal notations and relationship to the last previous issue.

Custodians:

Army - CR
Navy - EC
Air Force - 85
NASA - NA
DLA - CC

Preparing activity:

DLA - CC

(Project 5961-2015-028)

* NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <https://assist.dla.mil/>.